

**What is claimed is:**

1. A Semiconductor device comprising:

a plurality of IC chips that are connected each other by wiring and disposed on a substrate;

5 wherein said each IC chip is connected to outside said substrate by input wiring and output wiring; and

a transistor element that serves as an operation checking switch for said each IC chip is inserted in series into said wiring connecting between said IC chips.

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2. The semiconductor device according to claim 1, wherein said transistor element serves as a damping resistor.

3. The semiconductor device according to claim 1, wherein  
15 a termination resistance is formed on said wiring connecting between said IC chips.

4. The semiconductor device according to claim 1, wherein said transistor element is a depletion mode FET.

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5. The semiconductor device according to claim 2, wherein said transistor element and a resistance automatic compensation circuit are connected.

25 6. The semiconductor device according to claim 3, wherein said termination resistance and said resistance automatic compensation circuit are connected.

7. The semiconductor device according to claim 1, wherein  
30 said substrate is a silicon substrate.

8. The semiconductor device according to claim 1, wherein said substrate is a glass substrate.